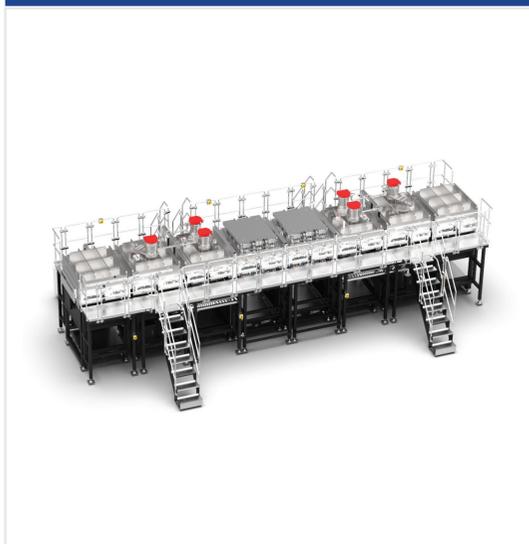


Fully Automated AMB Substrate Manufacturing Equipment

The Power Module Manufacturing equipment realizes low-temperature vacuum bonding by sputtering and brazing metals based on AMB technology. This is followed by processes such as etching and printing, with full process automation to maximize productivity and efficiency, optimize quality, and reduce costs.



Inline Sputter (Horizontal Type)



Specification

Layout	12,010mm x 7,059mm x 3,560mm
Weight	about 30,000kg
Pass Line	2,450mm
Substrate Size	140mm x 190mm ; various sizes available
Power	AC 200 ~ 440V
Cathode Type	Magnetron Rotary Cathode (DC or Pulsed DC)
Target	Metal Alloy Composite

Sputter (Batch Type)



Specification

Layout	3,900mm x 1,900mm x 2,880mm
Weight	about 5,000kg
Substrate Size	140mm x 190mm ; various sizes available
Power	AC 200 ~ 440V
Cathode Type	Single Magnetron Cathode (DC or Pulsed DC)
Target	Metal Alloy Composite

Brazing Furnace



Specification

Layout	3,000mm x 3,000mm x 3,200mm
Weight	about 6,000kg
Operating Temp	Up to 1,300°C
Degree of Vac	5 × 10 ⁻⁶ Torr
Power	AC 220V